

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT5191949

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
AMRUTHAVALLI PALLAVI ALUR	09/12/2018
SRI RANGA SAI BOYAPATI	09/12/2018
ROBERT ALAN MAY	09/12/2018
ISLAM A. SALAMA	03/01/2018
ROBERT L. SANKMAN	09/12/2018
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	INTEL CORPORATION
<b>Street Address:</b>	2200 MISSION COLLEGE BLVD.
<b>City:</b>	SANTA CLARA
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	95054
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15853330
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Email:</b>	request@slwip.com
<b>Correspondent Name:</b>	SCHWEGMAN LUNDBERG & WOESSNER, P.A.
<b>Address Line 1:</b>	P.O. BOX 2938
<b>Address Line 4:</b>	MINNEAPOLIS, MINNESOTA 55402
<b>ATTORNEY DOCKET NUMBER:</b>	1884.354US1
<b>NAME OF SUBMITTER:</b>	CARLEE DAVICH
<b>SIGNATURE:</b>	/Carlee Davich/
<b>DATE SIGNED:</b>	10/17/2018
<b>Total Attachments: 5</b>	
source=1884.354US1 Assignment#page1.tif	
source=1884.354US1 Assignment#page2.tif	

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RECORDATION FORM COVER SHEET  
PATENTS ONLY

Atty Ref/Docket No.: (D148643-US) 1884.354US1

Patent and Trademark Office

To the Director of the U.S. Patent and Trademark Office: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Amruthavalli Pallavi Alur, Sri Ranga Sai Boyapati, Robert  
Alan May, Islam A. Salama, Robert L. Sankman

Additional name(s) of conveying party(ies) attached?

☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Other

Execution Date: September 12, 2018, September 12,  
2018, September 12, 2018, March 1, 2018, September 12,  
2018

2. Name and address of receiving party(ies):

Name: Intel Corporation

Street Address: 2200 Mission College Blvd.

City: Santa Clara State: CA Zip: 95054

Country: United States of America

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)

Serial No. 15/853,330

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence  
concerning document should be mailed:

Name: John N. Greaves

Address:

Schwegman Lundberg & Woessner, P.A.  
P.O. Box 2938  
Minneapolis, Minnesota 55402

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41):\$ 0.00

☐ Enclosed


☐ Authorized to be charged to deposit account  
190743

8. Please charge any additional fees or credit any over  
payments to our Deposit Account No.: 190743

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of  
the original document.



17 October 2018

John N. Greaves/Reg. No. 40,362

Name of Person Signing

Signature

Date

Total number of pages including cover sheet: 5

Mail documents to be recorded with required cover sheet information to:

**Commissioner of Patents and Trademarks**  
**Mail Stop Assignment Recordation Services**  
**P.O. Box 1450**  
**Alexandria, VA 22313-1450**

**PATENT**  
**REEL: 047193 FRAME: 0016**

## **ASSIGNMENT**

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

**<Amruthavalli Pallavi Alur, Sri Ranga Sai Boyapati, Robert Alan May, Islam A. Salama,  
Robert L. Sankman>**

hereby sell, assign, and transfer to:

### **Intel Corporation**

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95054 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all other countries, in and to any and all inventions and improvements that are disclosed in the application for the patent entitled:

### **EMBEDDED MULTI-DIE INTERCONNECT BRIDGE PACKAGES WITH LITHOTGRAPHICALLY FORMED BUMPS AND METHODS OF ASSEMBLING SAME**

**(I hereby authorize and request any attorney having appropriate authority from the assignee to insert on the designated lines below, the filing date and application number of said application when known.)**

which was filed on **December 22, 2017** as

**United States of America** Application Number **15/853,330**

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all Additional Applications, and all other patent applications that have been or shall be filed in the United States and all other countries and international filing offices on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all other countries and international filing offices on said inventions and improvements; and in and to all rights of priority resulting from the filing of said applications; as used herein "Additional Applications" includes but is not limited to design, utility, utility model, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and national phase applications on said inventions and improvements;

and agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all Additional Applications, and all other patent applications on any and all said inventions and improvements; execute

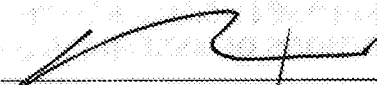
all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

  
Amruthavalli Pallavi Alur

9/12/18

Date Signed

  
Sri Ranga Sai Boyapati

9/12/18

Date Signed

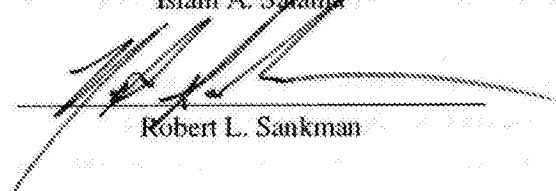
  
Robert Alan May

9/12/18

Date Signed

  
Islam A. Salama

Date Signed

  
Robert L. Sankman

9/12/18

Date Signed

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and agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all Additional Applications, and all other patent applications on any and all said inventions and improvements; execute

all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

\_\_\_\_\_  
Amruthavalli Pallavi Ahur

\_\_\_\_\_  
Date Signed

\_\_\_\_\_  
Sri Ranga Sai Boyapati

\_\_\_\_\_  
Date Signed

\_\_\_\_\_  
Robert Alan May

\_\_\_\_\_  
Date Signed

\_\_\_\_\_  


Islam A. Salama

\_\_\_\_\_  
03/01/2018

Date Signed

\_\_\_\_\_  
Robert L. Sankman

\_\_\_\_\_  
Date Signed